

PRODUCT BRIEF | VT-Stack Packaging

# MEMORY STACKING FOR EMBEDDED SOLUTIONS

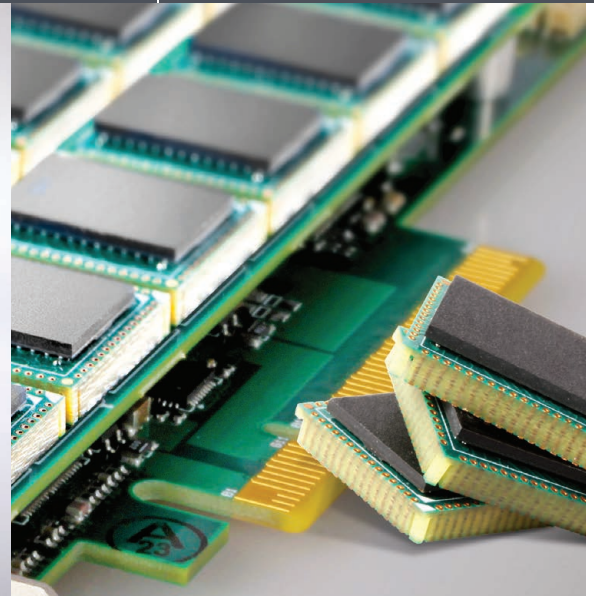
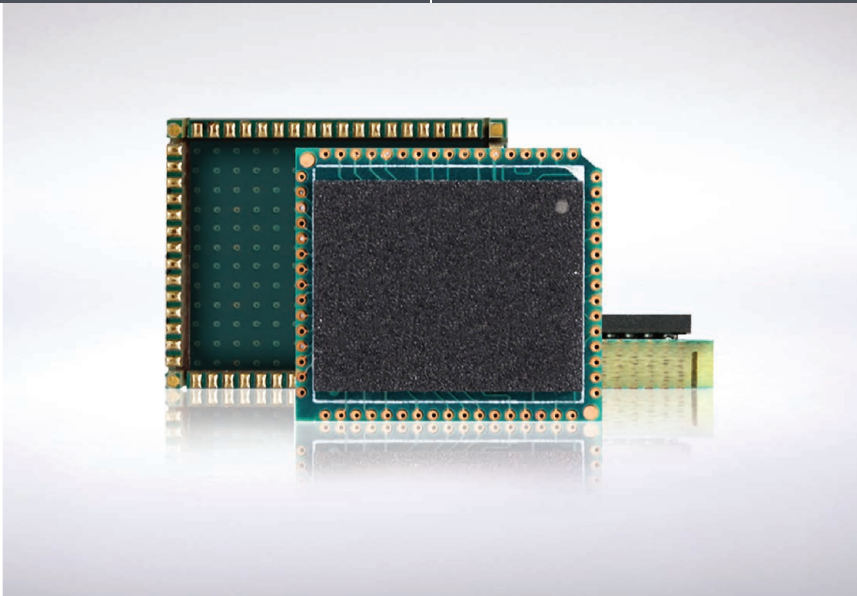
Viking Technology's 3rd Generation of Patented stacking, the VT-Stack™, enables OEM customers that are designing solutions with DRAM, NAND Flash or even next generation memory technologies such as MRAM, to optimize the performance and design cycle of their products.

## FEATURES

- ▶ Increased memory capacity
- ▶ Cost Effective
- ▶ Faster Time-to-Market (TTM)
- ▶ Stacking design support: DRAM, NAND & Persistent Memories

## APPLICATIONS SERVED

Enterprise markets – Highest DRAM Capacity Support	Embedded/Industrial markets – Ultra small form factor capacity	Military – SWaP Optimized
High Density SSD (Card, Module, Down-Board)	Embedded Products (uServer, Industrial PCs)	AdvancedTCA, MicroTCA



# MEMORY STACKING FOR EMBEDDED SOLUTIONS

## DRAM STACKING

Designing the highest density memory module solutions typically requires multi-die packaged DRAM (DDP or QDP). These multi-die packaged DRAMs have significant cost premiums, due to compound yield loss at test. Viking's VT-Stack™ Technology allows for ultimate flexibility of configuration, lower cost of device, and most importantly supply chain flexibility.

VT-Stack™ Technology supports high density DIMMs for servers in enterprise markets, as well as small form factor solutions for telecommunication, embedded and industrial markets.

## DRAM MODULES WITH VT-STACK

FORM FACTOR	TECHNOLOGY	SPEED	DENSITIES
LRDIMM	DDR4/DDR3	Up to 2666 MT/s	Up to 128GB
RDIMM	DDR4/DDR3	Up to 2666 MT/s	Up to 128GB
VLP RDIMM	DDR4/DDR3	Up to 2666 MT/s	Up to 64GB
VLP MiniRDIMM	DDR4/DDR3	Up to 2666 MT/s	Up to 64GB
VLP SORDIMM	DDR4/DDR3	Up to 2666 MT/s	Up to 64GB

## FLASH STACKING

VT-Stack™ Technology for NAND Flash allows for the highest capacity solutions in the smallest volume. Whether the interface is PCIe, SAS, SATA or other, Viking's VT-Stack™ Technology can double the capacity of the drive within the same footprint.

VT-Stack™ Technology for NAND Flash supports higher density designs to enable form factors such as PCIe Half-height/Half-length. The design also allows for SLC, MLC and TLC support with conformal coating options.



### Global Locations

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